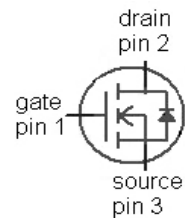
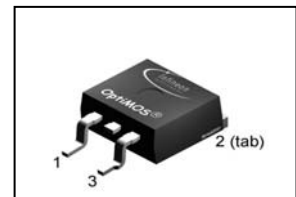


**OptiMOS<sup>®</sup> Power-Transistor**
**Features**

- N-channel Logic Level - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- **Green package (lead free)**
- Ultra low Rds(on)
- 100% Avalanche tested

**Product Summary**

$V_{DS}$	55	V
$R_{DS(on),max}$ (SMD version)	64	mΩ
$I_D$	19	A

**PG-TO252-3-11**


Type	Package	Marking
IPD15N06S2L-64	PG-TO252-3-11	2N06L64

**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25\text{ °C}$ , $V_{GS}=10\text{ V}$	19	A
		$T_C=100\text{ °C}$ , $V_{GS}=10\text{ V}^{1)}$	13	
Pulsed drain current <sup>1)</sup>	$I_{D,pulse}$	$T_C=25\text{ °C}$	76	
Avalanche energy, single pulse	$E_{AS}$	$I_D=15\text{ A}$	43	mJ
Gate source voltage	$V_{GS}$		±20	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}$	47	W
Operating and storage temperature	$T_j, T_{stg}$		-55 ... +175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Thermal characteristics**

Thermal resistance, junction - case	$R_{thJC}$		-	-	3.2	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$		-	-	100	
SMD version, device on PCB	$R_{thJA}$	minimal footprint	-	-	75	
		6 cm <sup>2</sup> cooling area <sup>2)</sup>	-	-	50	

**Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified**
**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	55	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=14\text{ }\mu\text{A}$	1.2	1.6	2.0	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	0.01	1	$\mu\text{A}$
		$V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ °C}^{1)}$	-	1	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=13\text{ A}$	-	61	85	m $\Omega$
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=13\text{ A}$	-	47	64	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics<sup>1)</sup>**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	354	-	pF
Output capacitance	$C_{oss}$		-	103	-	
Reverse transfer capacitance	$C_{rss}$		-	38	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=30\text{ V}, V_{GS}=10\text{ V},$ $I_D=15\text{ A}, R_G=20\ \Omega$	-	4	-	ns
Rise time	$t_r$		-	14	-	
Turn-off delay time	$t_{d(off)}$		-	21	-	
Fall time	$t_f$		-	12	-	

**Gate Charge Characteristics<sup>1)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=44\text{ V}, I_D=19\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	1	1.5	nC
Gate to drain charge	$Q_{gd}$		-	4	5	
Gate charge total	$Q_g$		-	11	13	
Gate plateau voltage	$V_{plateau}$		-	3.8	-	V

**Reverse Diode**

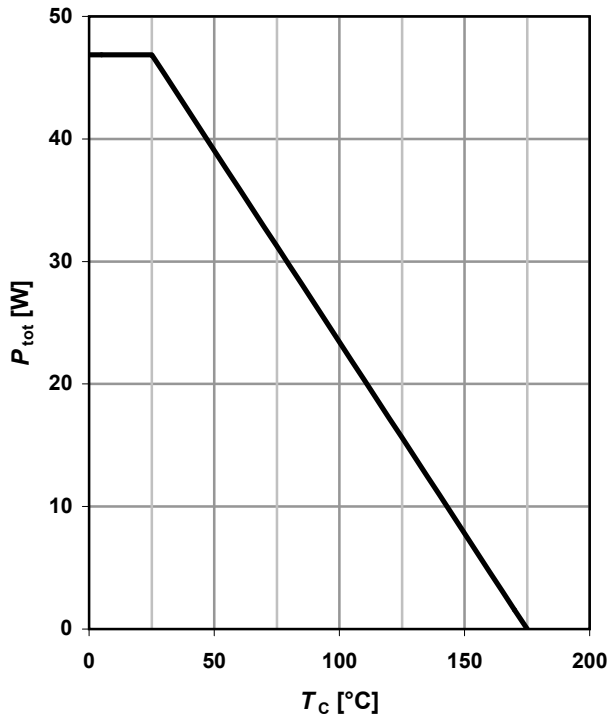
Diode continuous forward current <sup>1)</sup>	$I_S$	$T_C=25\text{ }^\circ\text{C}$	-	-	19	A
Diode pulse current <sup>1)</sup>	$I_{S,pulse}$		-	-	76	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=15\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	0.93	1.3	V
Reverse recovery time <sup>1)</sup>	$t_{rr}$	$V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	34	-	ns
Reverse recovery charge <sup>1)</sup>	$Q_{rr}$	$V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	32	-	nC

<sup>1)</sup> Defined by design. Not subject to production test.

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

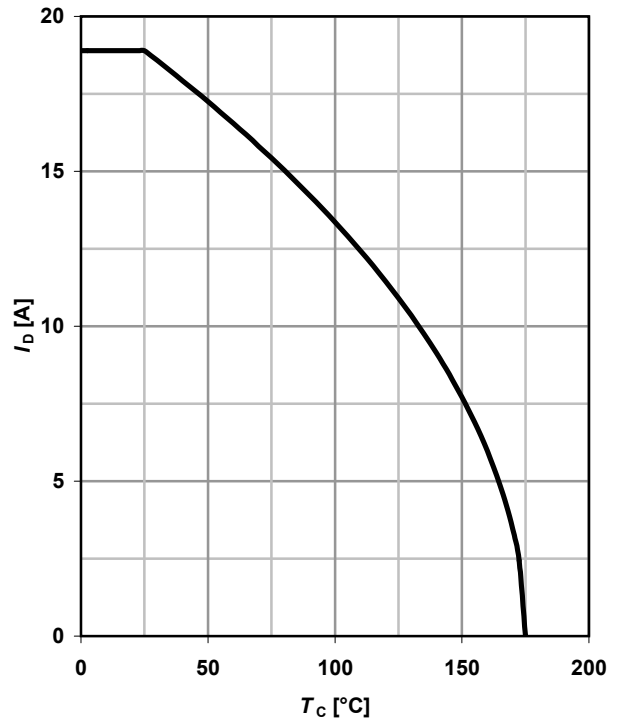
**1 Power dissipation**

$P_{tot} = f(T_C); V_{GS} \geq 4 \text{ V}$



**2 Drain current**

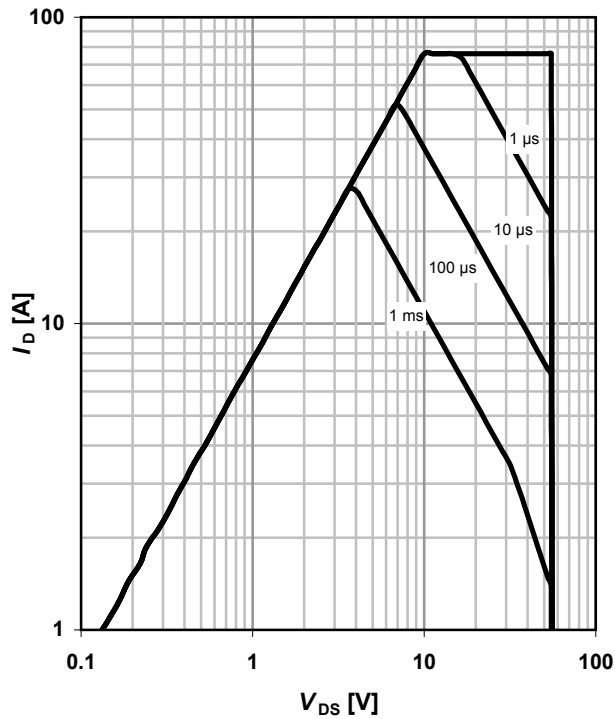
$I_D = f(T_C); V_{GS} \geq 10 \text{ V}$



**3 Safe operating area**

$I_D = f(V_{DS}); T_C = 25 \text{ °C}; D = 0$

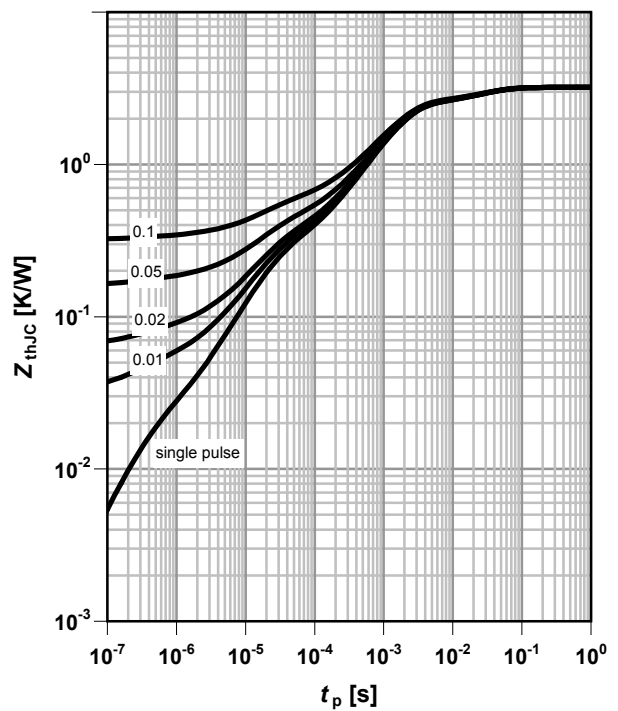
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

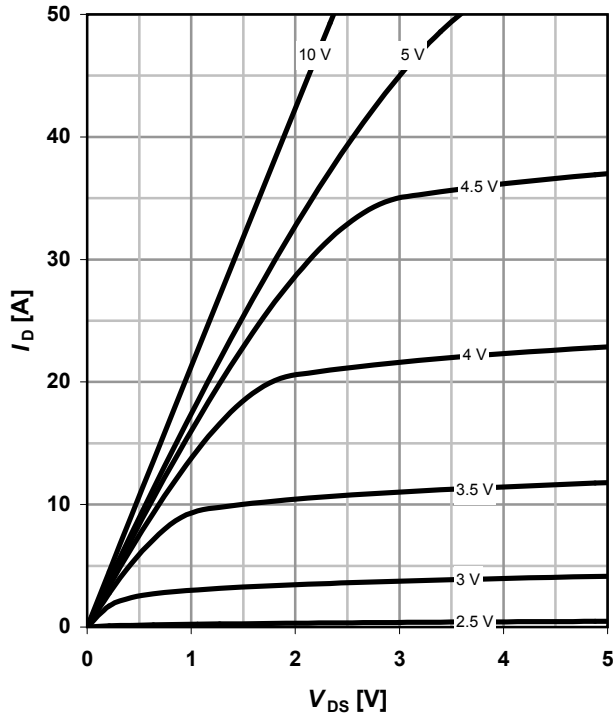
parameter:  $D = t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

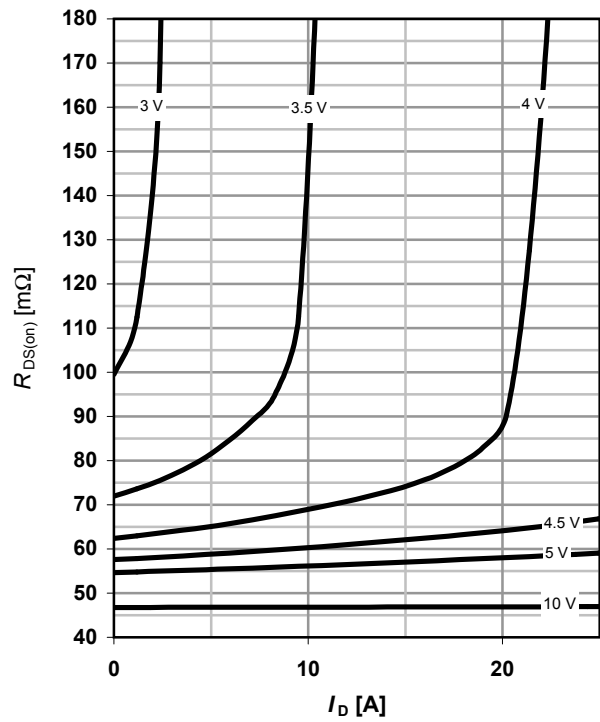
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

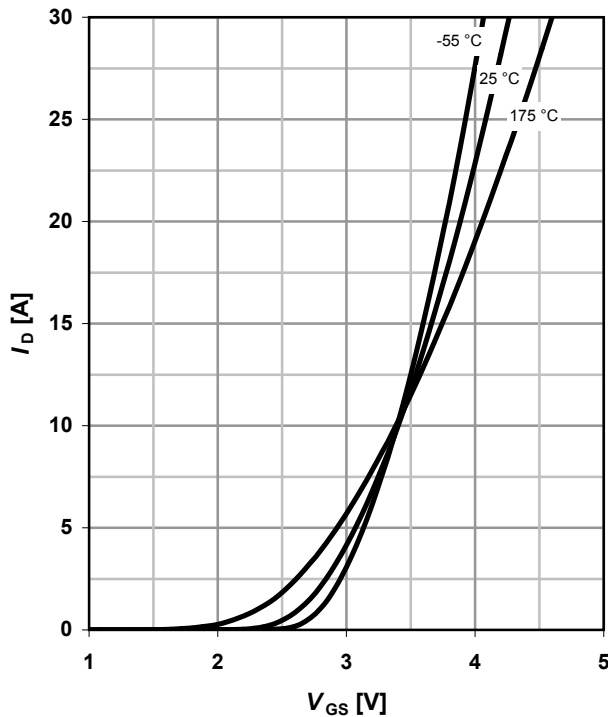
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); V_{DS} = 5\text{V}$

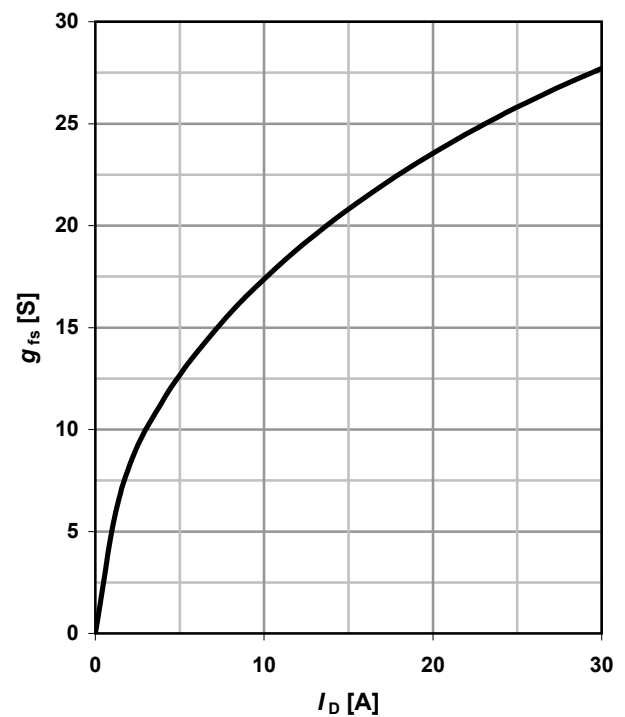
parameter:  $T_j$



**8 Typ. Forward transconductance**

$g_{fs} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

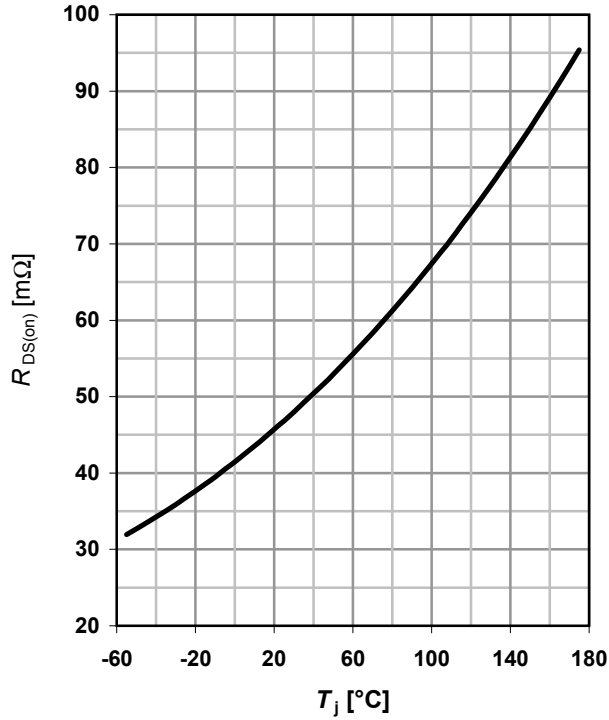
parameter:  $g_{fs}$



**9 Typ. Drain-source on-state resistance**

$R_{DS(ON)} = f(T_j)$

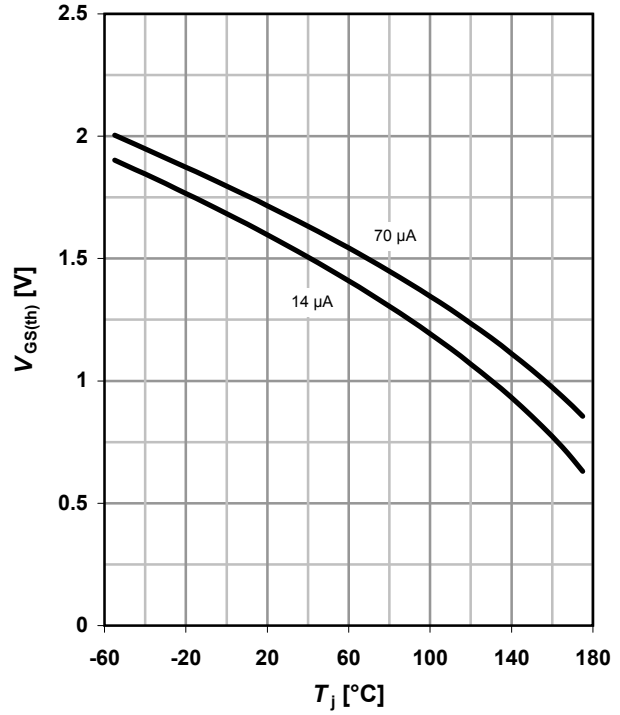
parameter:  $I_D = 8\text{ A}$ ;  $V_{GS} = 10\text{ V}$



**10 Typ. gate threshold voltage**

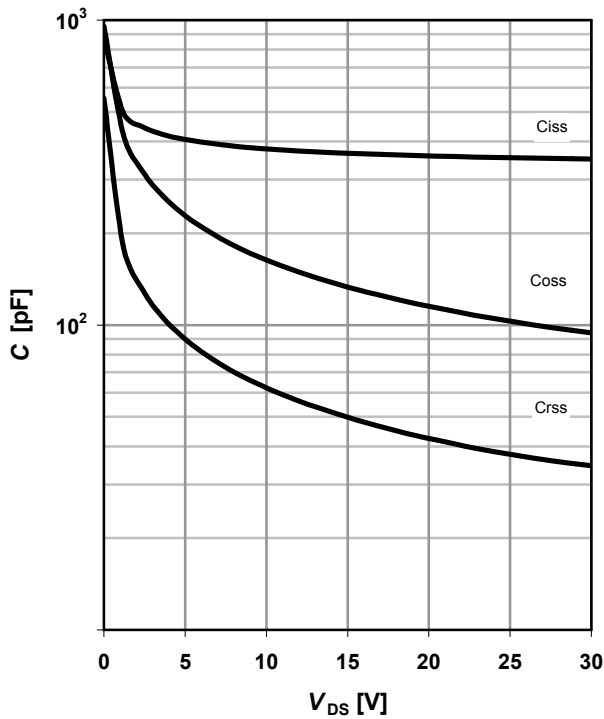
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**11 Typ. capacitances**

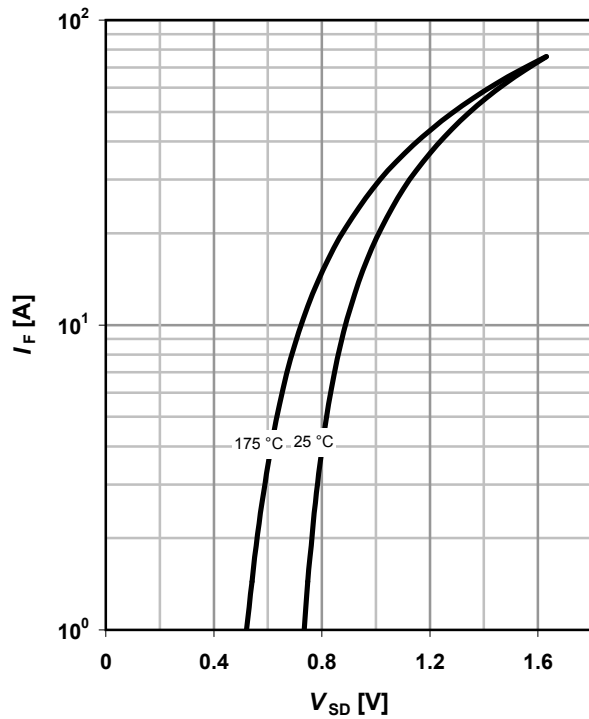
$C = f(V_{DS}); V_{GS} = 0\text{ V}; f = 1\text{ MHz}$



**12 Typical forward diode characteristics**

$I_F = f(V_{SD})$

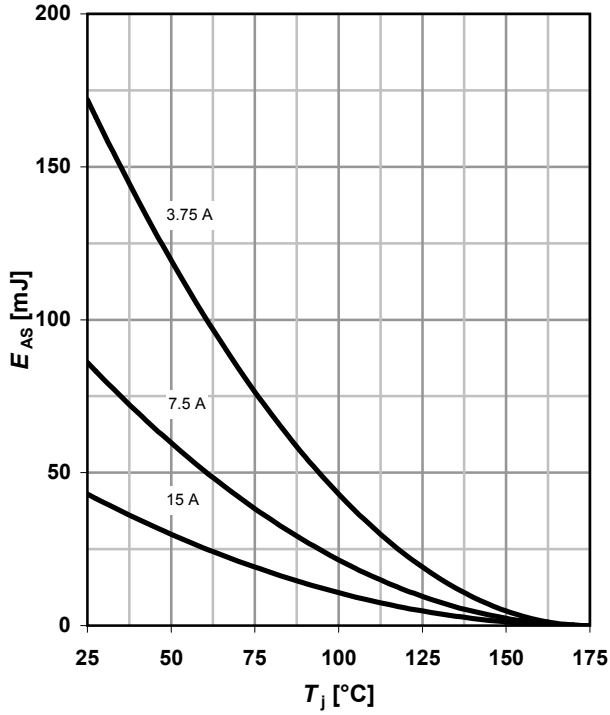
parameter:  $T_j$



**13 Typical avalanche energy**

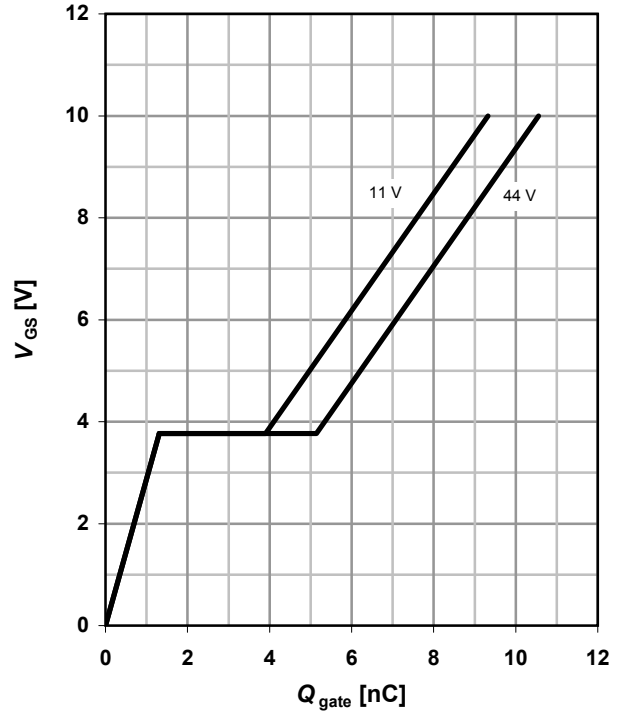
$E_{AS} = f(T_j)$

parameter:  $I_D$



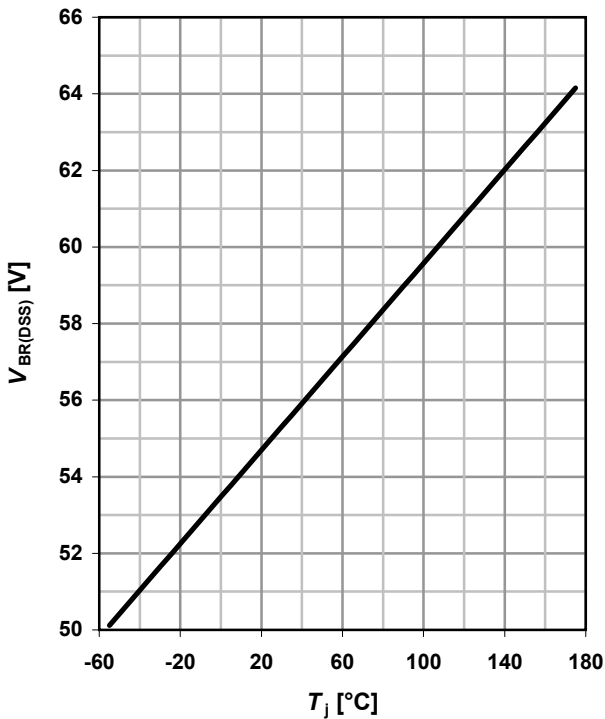
**14 Typ. gate charge**

$V_{GS} = f(Q_{gate}); I_D = 19 \text{ A pulsed}$



**15 Typ. drain-source breakdown voltage**

$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$



**16 Gate charge waveforms**



**Published by**  
**Infineon Technologies AG**  
**Am Campeon 1-12**  
**D-85579 Neubiberg**  
**© Infineon Technologies AG 1999**  
**All Rights Reserved.**

**Attention please!**

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

**Information**

For further information on technology, delivery terms and conditions and prices, please contact your nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com))

**Warnings**

Due to technical requirements, components may contain dangerous substances.  
For information on the types in question, please contact your nearest Infineon Technologies Office.

Infineon Technologies' components may only be used in life-support devices or systems with the expressed written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.